BEFORE

AFTER

VACUUM CHAMBER PM TECHNIQUE
ALCATEL COMPTECH 2460 PROCESS CHAMBER

OBJECTIVE:

TO PM THE ALCATEL COMPTECH 2460 PROCESS CHAMBER IN AN EFFECTIVE AND TIMELY MANNER, WHILE IMPROVING TOOL RECOVERY AND PARTICLE PERFORMANCE

NOTE: THE TOOL THAT WAS PM'D HAD NEVER HAD ALL OF THE DEPOSITION REMOVED. IN ORDER TO KEEP THE CHAMBER IN OPTIMUM CONDITION A REGULARLY SCHEDULED CHAMBER PM IS RECOMMENDED

Vacuum Chamber: ALCATEL COMPTECH 2460

Vacuum Chamber Process Residue: PROCESS INDUCED RESIDUE (AL_2O_3)

Vacuum Chamber Components: PROCESS CHAMBER

Old Procedure: Scrape/vacuum out excess build-up deposition (NOT ENTIRELY REMOVED)
Recovery time: 12 to 16 hours

New Procedure: 3 hours using 140D/280D ScrubPADS, UltraSOLV® Sponge, and MiraWIPES®
Recovery time: TBD

Vacuum Chamber Products:

Note: Products used for initial clean. Once regular PM cycle is developed, products may change

- **x** (3) HT4514D-10-1 140 Grit Diamond ScrubPAD
- x (1) HT4528D-10-1 280 Grit Diamond ScrubPAD
- x (1) HT4754 UltraSOLV® Sponge
- x (3) HT5790S-5 MiraWIPES®

ALCATEL 2460 PROCESS CHAMBER PM PROCEDURE:

View "How to" instructional videos on http://www.foamtecintlwcc.com/flash/

Step 1: Using proper procedures and **safety guidelines**, shutdown and prepare Alcatel 2460 Process Chamber for wet clean

Step 2: Fill FT1301 plastic container with approximately 12oz of DI water and place next to process chamber (See Fig 1)

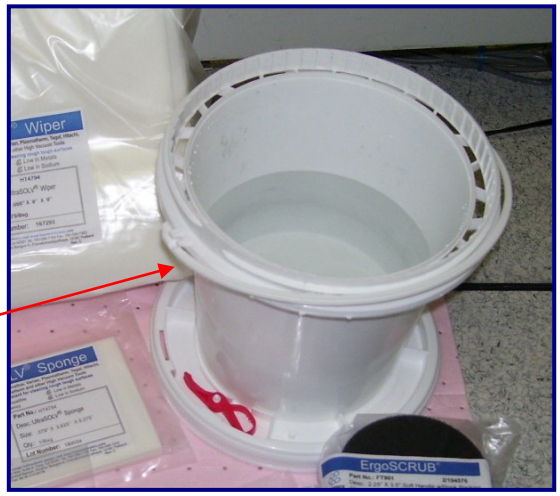


Fig 1: FT1301 plastic container with DI water

Step 3: Place HT4514D 140 Grit Diamond ScrubPAD and HT4754 UltraSOLV® Sponge in container of DI water to moisten products (See Fig 2)

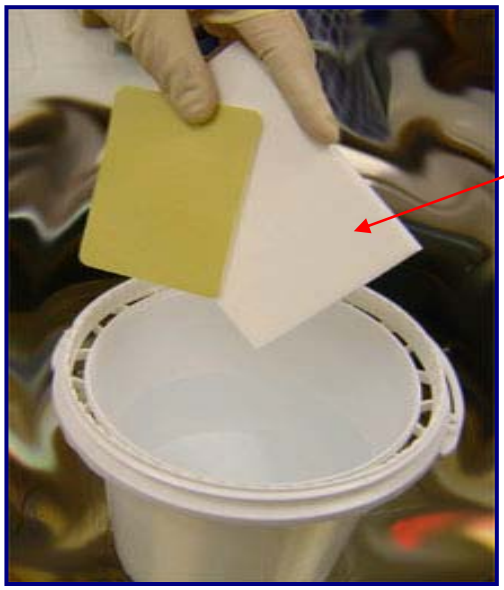


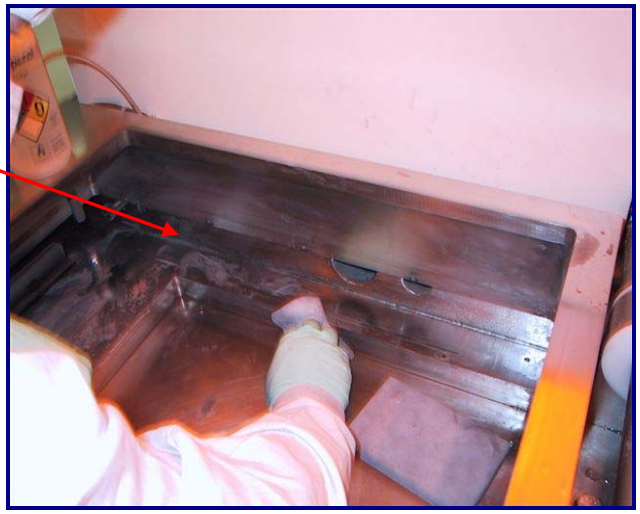
Fig 2: Place Diamond ScrubPAD and UltraSOLV® Sponge in container of DI water

ALCATEL 2460 PROCESS CHAMBER PM PROCEDURE (CONT'D):

Step 4: Take **lightly dampened** UltraSOLV® Sponge and wipe area of process chamber that is to be cleaned in order to remove flaking deposition from chamber

Step 5: Take **lightly dampened** 140 Grit Diamond ScrubPAD and scrub a small area of the process chamber (See Fig 3)

Fig 3: Scrubbing process chamber with Diamond ScrubPAD



NOTE: **REMEMBER IT IS NOT NECESSARY TO USE A LOT OF DI WATER DURING THIS SCRUB PORTION OF THE PM, ONLY ENOUGH TO KEEP DIAMOND ScrubPAD MOIST**

Step 6: After scrubbing a small area with the 140 Grit Diamond ScrubPAD, take the lightly dampened UltraSOLV® Sponge and wipe deposition from the scrubbed area

ALCATEL 2460 PROCESS CHAMBER PM PROCEDURE (CONT'D):

Step 7: As Diamond ScrubPAD loads-up with deposition, pull ScrubPAD across damp UltraSOLV® Sponge to properly unload (See Fig 4, 5 & 6)

Fig 4: ScrubPAD loaded with deposition

Fig 5: Pull ScrubPAD across UltraSOLV® Sponge

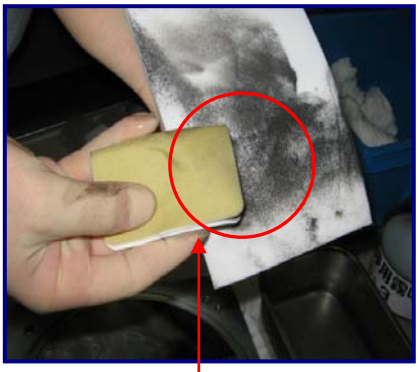


Fig 6: Unloaded ScrubPAD

Step 8: Unload UltraSOLV® as much as possible by placing it in container of DI water and **RINSE-OUT** thoroughly (See Fig 7 & 8)

Fig 7: Loaded-up UltraSOLV® Sponge

Fig 8: UltraSOLV® Sponge AFTER rinse

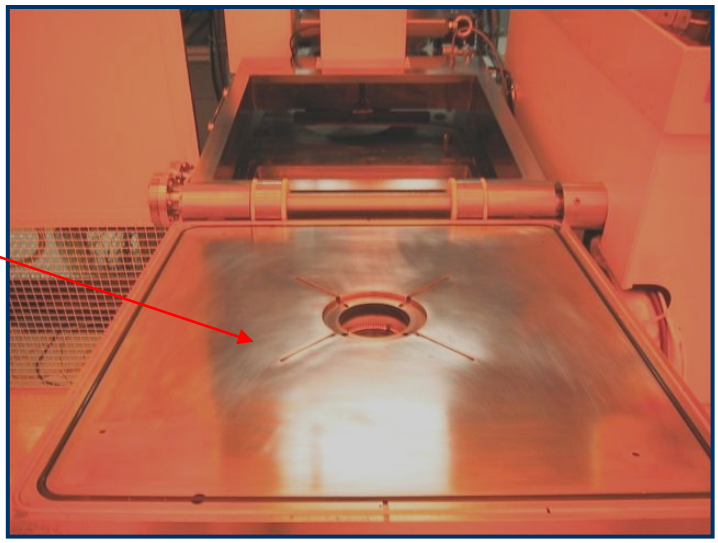
ALCATEL 2460 PROCESS CHAMBER PM PROCEDURE (CONT'D):

Step 14: After scrubbing a small area with the 280 Grit Diamond ScrubPAD use the lightly dampened UltraSOLV® Sponge to wipe deposition from the scrubbed area

Step 15: As ScrubPAD loads-up with deposition, pull ScrubPAD across damp UltraSOLV® Sponge to properly unload (See Step 7 and Step 8)

Step 16: Continue scrub-wipe-unload procedure until all process residue is removed from chamber lid (See Fig 11)

Fig 11: Clean chamber lid



Step 17: When scrub portion of wet clean is complete, prepare chamber for FINAL WIPE PROCEDURE by rinsing out UltraSOLV® Sponge with fresh DI water and performing a complete final process chamber wipe using the dampened UltraSOLV® Sponge